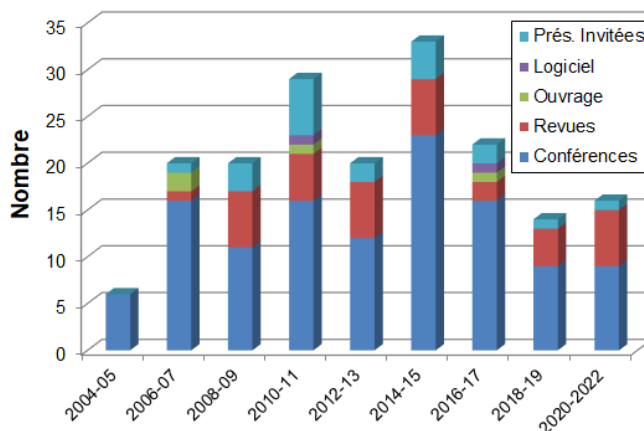


Liste des publications

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[CI70] C. Ghfiri, **A. Boyer**, A. Durier, C. Marot, S. Ben Dhia, "Construction of an Integrated Circuit Emission Model of a FPGA", 2016 Asia-Pacific International Symposium on Electromagnetic Compatibility and Signal Integrity, May 18 – 21, 2016, Shenzhen. **Prix du meilleur papier étudiant.**

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[CI78] N. Lacrampe, S. Serpaud, **A. Boyer**, S. Tran, "Radiated Susceptibility Investigation of Electronic Board from Near Field Scan Method", EMC Compo 2017, Saint Petersburg, Russia, July 2017.

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[CI82] C. Ghfiri, **A. Boyer**, A. Durier, S. Ben Dhia, C. Marot, "Modeling the internal activity of a FPGA for conducted emission prediction purpose", 2018 Joint IEEE EMC & APEMC Symposium, Singapour, May 14-17 2018.

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[CI85] **A. Boyer**, "A Rigorous Method to extrapolate Radiated Susceptibility from Near-Field Scan Immunity", EMC Europe 2019, 2-6 Sept 2019, Barcelona, Spain.

[CI86] S. Serpaud, **A. Boyer**, S. Ben Dhia, " Sequential adaptive sampling algorithm to reduce the near-field measurement time", EMC Europe 2019, 2-6 Sept 2019, Barcelona, Spain.

[CI87] N. El Belghiti Alaoui, A. Cassou, P. Tounsi, **A. Boyer**, A. Viard, " Using infrared thermal responses for PCBA production tests: Feasibility study ", 30th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis (ESREF 2019), Aalborg, Denmark, 23-26 Sept. 2019.

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[CI96] B. Guendouz, K. Abouda, **A. Boyer**, S. Ben Dhia, P. Perruchoud, "A Simple Analytical Approximation to evaluate Noise Levels and Maximum Coupling Frequencies During DPI Simulations on BMS IC", Accepted

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2005

[CN1] **A. Boyer**, S. Bendhia, J.L. Levant, M. Ramdani, B. Vrignon, « Modélisation d'un Boîtier TQFP144 par mesures et simulation », 4èmes JFMMA & TELECOM 2005, Rabat, Maroc, 23 - 25 mars 2005.

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[CN4] **A. Boyer**, S. Bendhia, « Design d'un Agresseur Champ Proche dédié à l'Etude CEM des System-in-Package », JNRDM06 – Rennes – France – 10 -12 mai 2006.

2007

[CN5] **A. Boyer**, « Caractérisation et Modélisation de la Susceptibilité d'un Circuit Intégré par une Méthode de Scan Champ Proche », Journée l'école doctorale GEET, Toulouse, 8 mars 2007.

[CN6] L. Bouhouch, **A. Boyer**, « Amélioration des Performances CEM d'un Microcontrôleur à l'aide d'un Film de Matériau Ferromagnétique », 5èmes JFMMA & TELECOM 07, Fès, Maroc, 14 – 16 mars 2007.

[CN7] **A. Boyer**, S. Akue Boulingui, E. Sicard, S. Baffreau, « Méthodologie de Prédiction des Risques d'Interférences dans un Couplage Puce à Puce », 5èmes JFMMA & TELECOM 07, Fès, Maroc, 14 – 16 mars 2007.

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[CN10] A. C. Ndoye, **A. Boyer**, E. Sicard, S. Serpaud, F. Lafon, « Une plateforme collaborative de service en modélisation CEM des Composants », Telecom 2009, Agadir, 11-13 Mars 2009.

2010

[CN11] E. Sicard, **A. Boyer**, « IC-EMC: A Dedicated environment for predicting electromagnetic compatibility of integrated circuits », 2EMC 2010, Rouen, 18 – 19 Novembre 2010.

[CN12] E. Sicard, **A. Boyer**, « Une approche éducative de la compatibilité électromagnétique des circuits intégrés », JPCNFM 2010, 22 – 24 Novembre 2010, Saint Malo.

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[CN13] E. Sicard, **A. Boyer**, « Retour d'expérience d'une formation Eurodots en compatibilité électromagnétique des circuits intégrés », JPCNFM 2012, 28-30 novembre 2012, Saint Malo.

2014

[CN14] V. Tomasevic, **A. Boyer**, S. Ben Dhia, " Développement d'un capteur sur puce afin d'étudier le couplage parasite dans les circuits intégrés de type "Smart Power", 17e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2014, Clermont-Ferrand, 1-3 juillet 2014.

[CN15] H. Huang, **A. Boyer**, S. Ben Dhia, " Impact du vieillissement thermique sur l'émission d'un convertisseur Buck", 17e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2014, Clermont-Ferrand, 1-3 juillet 2014.

2015

[CN16] E. Sicard, **A. Boyer**, "IC-EMC - Simulation of Electromagnetic Compatibility of Integrated Circuits", Salon Microwave & RF 2015, Paris.

2016

[CN17] C. Ghfiri, **A. Boyer**, A. Durier, S. Ben Dhia, "Construction d'un modèle ICEM pour prédire l'émission électromagnétique d'un FPGA", 18e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2016, Rennes, 11-13 juillet 2016.

[CN18] **A. Boyer**, "Amélioration de la résolution spatiale de scan champ proche en injection", 18e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2016, Rennes, 11-13 juillet 2016.

[CN19] **A. Boyer**, " Caractérisation et modélisation de l'effet du vieillissement sur l'intégrité de signal d'un buffer d'horloge utilisé dans un calculateur aéronautique", ANADEF 2016, Toulouse.

2021

[CN20] **A. Boyer**, A. Durier, S. Ben Dhia, « Une nouvelle sonde de mesure de tension induite pour l'investigation en immunité rayonnée », 20e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2021, Lyon, Virtuel, 13-15 avril 2021.

[CN21] S. Chetouani, **A. Boyer**, S. Ben Dhia, S. Serpaud, « Application des méthodes de mesures indirectes de paramètres " S " en vue de la gestion de l'obsolescence des composants en immunité conduite », 20e Colloque International et Exposition sur la Compatibilité Electromagnétique CEM2021, Lyon, Virtuel, 13-15 avril 2021.

Présentations invitées & Workshops

2007

[PIW1] S. Ben Dhia, **A. Boyer**, « Electromagnetic compatibility of integrated circuits». One day tutorial, Feng Chia University (FCU), July 16th, 2007, Taiwan.

2008

[PIW2] **A. Boyer**, S. Ben Dhia, « Fiabilité des circuits intégrés face aux agressions électromagnétiques », ANADEF 2008, Port d'Albret, France

[PIW3] **A. Boyer**, S. Ben Dhia, A. C. Ndoye, "EMC/EMI Issues for DSM: New Challenges", Workshop on Long Term Reliability in DSM, Noordwijk (Netherland), October 3rd, 2008.

2009

[PIW4] S. Ben Dhia, **A. Boyer**, "Still EMC Compliant?", Workshop on Long Term Reliability in DSM, Arcachon, October 9th, 2009.

2010

[PIW5] **A. Boyer**, "Introduction to the modeling and simulation of electromagnetic compatibility of integrated circuits", Tutorial, 2010 Asia-Pacific International Symposium on Electromagnetic Compatibility, April 12th, 2010, Beijing, China.

[PIW6] **A. Boyer**, « Résultats du projet R&T CNES : CEM et vieillissement des composants », CCT MCE, Tutorial Décharges Electrostatiques (ESD) : du composant au système, Toulouse, 15 décembre 2010.

2011

[PIW7] **A. Boyer**, S. Ben Dhia, "Initiation to the modeling and simulation of susceptibility of integrated circuits to electromagnetic interferences", Tutorial, 2011 Asia-Pacific International Symposium on Electromagnetic Compatibility, May 16th, 2011, Jeju Island, Korea.

[PIW8] S. Ben Dhia, **A. Boyer**, "La CEM des Circuits Intégrés", Présentation invitée à l'école d'été du GT6 (CEM) du GDR Ondes, ENS Cachan, 30 août au 2 septembre 2011.

[PIW9] **A. Boyer**, E. Sicard, « IC Immunity Modeling », Tutorial, 2011, EMC Compo 2011, November 6th 2011, Dubrovnik, Croatia.

[PIW10] **A. Boyer**, « Scan champ proche pour l'injection localisée de perturbations – Robustesse électromagnétique », Workshop E-SAFE, LAAS-CNRS, 8 décembre 2011, Toulouse, France.

2012

[PIW11] **A. Boyer**, « Scan champ proche pour l'injection localisée de perturbations pour l'analyse de l'immunité des circuits intégrés », Séminaire CEM – Aide à la conception d'équipements électroniques – NEXIO, LAAS-CNRS, Toulouse, 4 avril 2012.

[PIW12] **A. Boyer**, « Investigation de l'immunité des circuits intégrés par la méthode DPI », Séminaire CEM – Ingénierie d'essais – NEXIO, LAAS-CNRS, Toulouse, 13 novembre 2012.

2014

[PIW13] **A. Boyer**, « Fiabilité électromagnétique des COMPOSANTS NUMERIQUES ET systèmes électroniques à long terme », DAS SE2L, Journée Thématique « Evolutions technologiques dans le domaine de l'électronique numérique (composants), impacts vis-à-vis des applications embarquées » - 18 septembre 2014 - Toulouse.

[PIW14] L. Chusseau, **A. Boyer**, B. Vrignon, J. Shepherd, « E-Mata-Hari Project », Freescale Fritech, 4 décembre 2014.

2015

[PIW15] **A. Boyer**, B. Vrignon, "Couplage Electromagnétique sur Circuits Intégrés », Journée champ proche, GDR Ondes, LAAS-CNRS, 19 juin 2015.

[PIW16] **A. Boyer**, "Analysis and modelling of passive device degradation for a long-term electromagnetic emission study of a DC-DC converter", EMC Compo 2015, Edimburgh, Scotland, November 2015.

2016

[PIW17] **A. Boyer**, "Détection de circuits intégrés contrefaits par mesure de l'empreinte électromagnétique", CCT MCE, Obsolescence des composants électroniques Actions et Réactions, Toulouse, 23 juin 2016.

2017

[PIW18] **A. Boyer**, "Learning EMC of ICs with IC-EMC", EMC Europe 2017, Angers, France, September 2017.

2018

[PIW19] **A. Boyer**, "Predict long-term evolution of EMC of ICs", NXP EMC Workshop, 23 mai 2018.

2021

[PIW20] F. Ruffat, F. Caignet, **A. Boyer**, « Modèle fréquentiel pour la modélisation des protections non linéaires des systèmes électroniques visant à prédire

l'impact d'agressions transitoires de forte puissance », 8e Journées d'études Electromagnétisme et Guerre Electronique (EMGE), Toulouse, France, 14 et 15 décembre 2021 (reporté en juin 2022 cause Covid).

Logiciels

[LO1] IC-EMC, a freeware dedicated to electromagnetic compatibility of integrated circuits. Version 2.5, 2011, www.ic-emc.org.

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